



February 2022

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#### N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BVDSS	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
201/	$29m\Omega$ @ V <sub>GS</sub> = $10V$	6.5A
20V	$35m\Omega$ @ V <sub>GS</sub> = $4.5V$	5.4A

## **Description**

This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## Applications

- General purpose interfacing switches
- Power management functions

## **Features**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN2053UQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

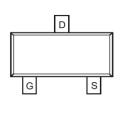
### **Mechanical Data**

- Package: SOT23
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e3)
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (Approximate)

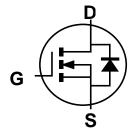




Top View



Top View



**Equivalent Circuit** 

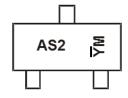
## Ordering Information (Note 4)

Part Number	Pankaga	Packing		
Part Number	Package	Qty.	Carrier	
DMN2053UQ-7	SOT23	3000	Tape & Reel	
DMN2053UQ-13	SOT23	10000	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## Marking Information



AS2 = Product Type Marking Code YM = Date Code Marking  $\overline{Y}$  = Last Digit of Year (ex: J = 2022) M = Month (ex: 1 = January)

Data Cada Kay

Date Code Rey												
Year	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	I	J	K	L	М	N	0	Р	R	S	Т	U
	1	1	1	1	1	l	1	l _	_	l _	l	_
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characte	eristic		Symbol	Value	Unit
Drain-Source Voltage			VDSS	20	V
Gate-Source Voltage		Vgss	±12	V	
Continuous Drain Current (Note 6)	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	lo	6.5 5.4	Α	
Pulsed Drain Current (380µs Pulse, D	uty Cycle = 1%)		I <sub>DM</sub>	22	А

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		PD	8.0	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	RθJA	160	°C/W
Total Power Dissipation (Note 6)		PD	1.3	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	93	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

# **Electrical Characteristics** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	1.0	μA	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	Vgs(TH)	0.5	0.95	1.2	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
			26	29		VGS = 10V, ID = 6A
Static Drain-Source On-Resistance			28	35	0	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A
Static Drain-Source On-Resistance	RDS(ON)	_	35	48	mΩ	V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 4A
			47	91		VGS = 1.8V, ID = 2A
Diode Forward Voltage	VsD		0.7	1.0	V	VGS = 0V, IS = 1A
DYNAMIC CHARACTERISTICS (Note 8)	•					
Input Capacitance	Ciss	_	414	_	pF	
Output Capacitance	Coss	_	58	_	pF	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, -f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	43	_	pF	1 = 1.0WHZ
Gate Resistance	Rg	_	3.6	_	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge	Qg	_	4.6	_	nC	
Gate-Source Charge	Qgs	_	0.5	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Drain Charge	Q <sub>gd</sub>	_	1.4	_	nC	ID = 6A
Turn-On Delay Time	t <sub>D(ON)</sub>	_	2.6	_	ns	
Turn-On Rise Time	t <sub>R</sub>	_	2.9	_	ns	V <sub>DD</sub> = 10V, V <sub>GS</sub> = 5V,
Turn-Off Delay Time	tD(OFF)	_	13.5	_	ns	$R_L = 1.7\Omega$ , $R_G = 6\Omega$
Turn-Off Fall Time	tF	_	3.8	_	ns	]
Reverse Recovery Time	t <sub>RR</sub>	_	6.8	_	ns	I <sub>F</sub> = 1.0A, di/dt = 100A/μs
Reverse Recovery Charge	Qrr	-	1.2	_	nC	$I_F = 1.0A$ , $di/dt = 100A/\mu s$

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing Notes:



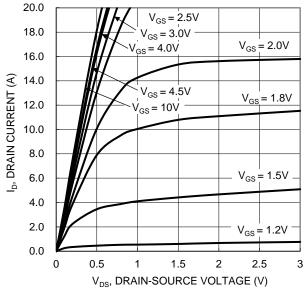


Figure 1. Typical Output Characteristic

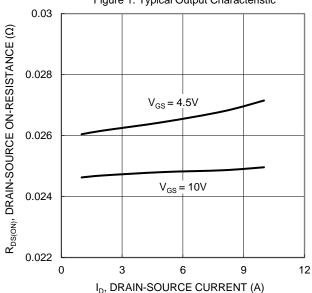


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

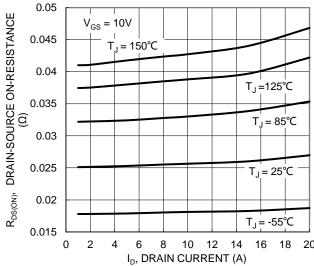


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

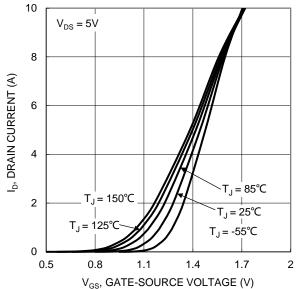


Figure 2. Typical Transfer Characteristic

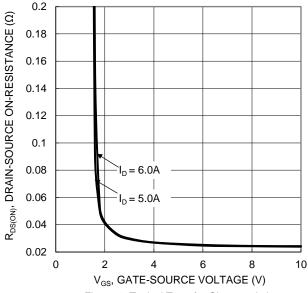


Figure 4. Typical Transfer Characteristic

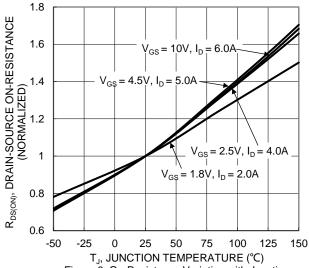


Figure 6. On-Resistance Variation with Junction Temperature



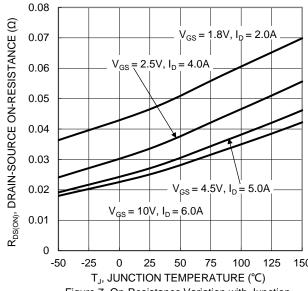


Figure 7. On-Resistance Variation with Junction Temperature

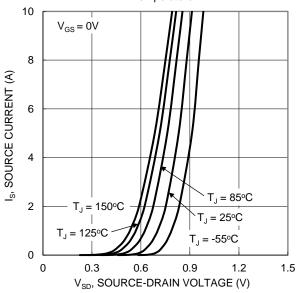


Figure 9. Diode Forward Voltage vs. Current

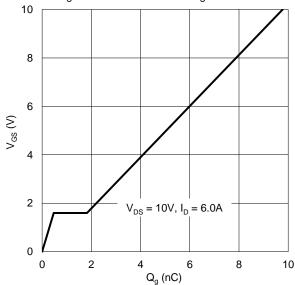


Figure 11. Gate Charge

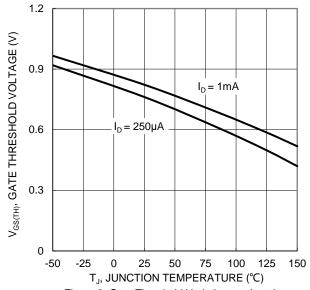


Figure 8. Gate Threshold Variation vs. Junction Temperature

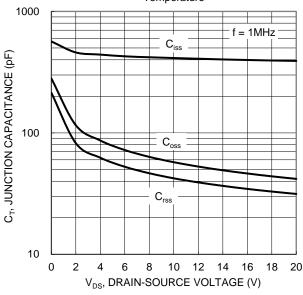
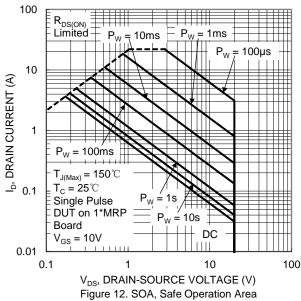


Figure 10. Typical Junction Capacitance





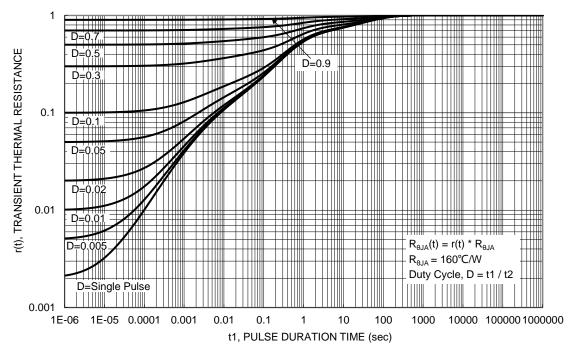


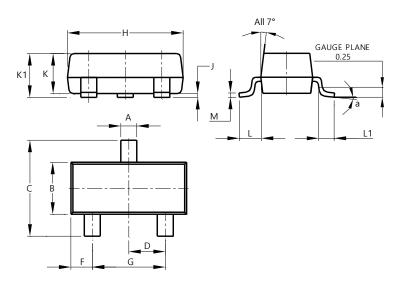
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT23

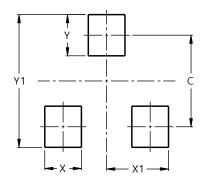


SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а	0°	8°					
All	Dimens	ions in	mm				

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT23



Dimensions	Value (in mm)
С	2.0
X	0.8
X1	1.35
Υ	0.9
V1	2.0



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